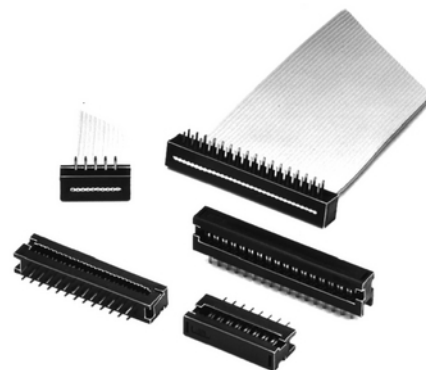


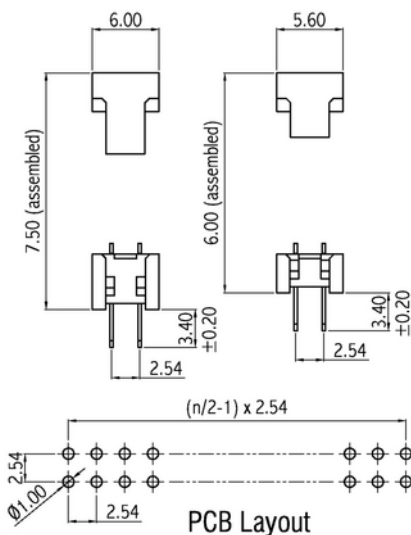
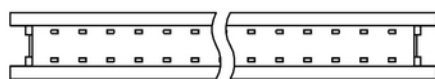
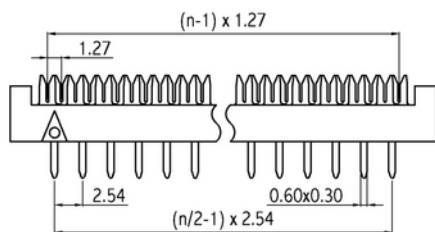
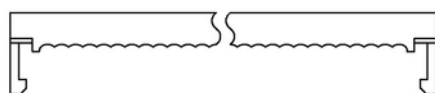
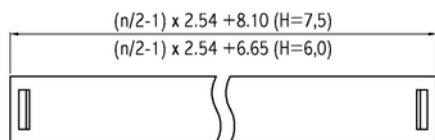
IDC Leiterplattenverbinder RM 2,54mm - BH 7,5 / 6,0mm IDC Printed Circuit Connectors, 2.54mm Pitch - 7.5mm / 6.0mm Profiles

Technische Daten / Technical Data

Isolierkörper	Thermoplastischer Kunststoff, nach UL94 V-0
Insulator	Thermoplastic, rated UL94 V-0
Kontaktmaterial	Kupferlegierung
Contact Material	Copper alloy
Kontaktoberfläche	Lt. Oberflächenoptionen, über Ni (1,3 ... 2,5µm)
Contact Surface	Acc. to options (see below), over Ni (1.3 ... 2.5µm)
Lötbarkeit	IEC 60512-12A
Solderability	IEC 60512-12A
Durchgangswiderstand	< 20mΩ
Contact Resistance	< 20mΩ
Isolationswiderstand	> 1000MΩ
Insulation Resistance	> 1000MΩ
Spannungsfestigkeit	500V _{AC}
Test Voltage	500V _{AC}
Nennstrom	1A
Current Rating	1A
Temperaturbereich	-40°C ... +105°C
Temperature Range	-40°C ... +105°C
Verarbeitung	Wellenlötverfahren
Processing	Wave soldering



© W+P PRODUCTS



Series	Contacts*	Plating*	Height*	Colour (Optional)
140	64	60	7,5	6
	08/10/14/16/18/ 20/22/24/26/28/ 30/34/40/50/ 60/64	50 Verzinkt (Standard) Tin plated (Standard) 60 Sel. Au/Sn (Standard) Duplex Plating (Standard) 00 Vergoldet (auf Anfrage) Gold plated (on request)	7,5 H=7,50 B=6,00mm 6 H=6,00 B=5,60mm	6 Grau (Standard: Schwarz) Grey (Standard: Black)

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** -
please replace by your specifications.

TEL +49 5223 98507-0
FAX +49 5223 98507-50

W+P PRODUCTS

E-MAIL sales@wpro.com
WEBSITE www.wpro.com

Informationen zum Wellen-Lötverfahren Wave Soldering Information

Empfehlungen für das Wellenlötverfahren Recommendations for Wave Soldering

Die Bauteile sollten bei einer Lötbadtemperatur von 260°C in max. 5 Sekunden verlötet werden.
Items should be soldered at a solder temperature of 260°C in 5 seconds max.

Empfohlenes Wellenlötprofil:
Recommended wave soldering profile:

